



HS 3120 Double Buffered 12-Bit MDAC

FEATURES

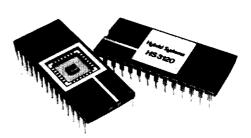
- Monolithic Construction
- 12 Bit Resolution
- 0.01% Non-Linearity
- µP Compatible
- 4-Quadrant Multiplication
- Latch-up Protected

DESCRIPTION

The HS 3120 is a precision monolithic 12-bit multiplying DAC with internal two-stage input storage registers for easy interfacing with microprocessor busses. It is packaged in a 28-pin DIP to give high I/O design flexibility.

DOUBLE BUFFERED — The input registers are sectioned into 3 segments of 4 bits each, all individually addressable. The DAC-register, following the input registers, is a parallel 12-bit register for holding the DAC data while the input registers are updated. Only the data held in the DAC register determines the analog output value of the converter.

MICRO PROCESSOR COMPATIBLE — The HS 3120 has been designed for great flexibility in connecting to busoriented systems. The 12 data inputs are organized into 3 independent addressable 4-bit input registers such that the HS 3120 can be connected to either a 4, 8 or 16-bit data bus. The control logic of the HS 3120 includes chip enable and latch enable inputs for flexible memory mapping. All



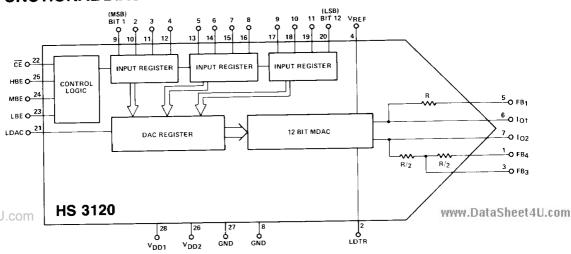
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controls are level-triggered to allow static or dynamic operation.

VERSATILE OUTPUTS — A total of 5 output lines are provided by the HS 3120 to allow unipolar and bipolar output connection with a minimum of external components. The feedback resistor is internal. The resistor ladder network termination is externally available, thus eliminating an external resistor for the 1 LSB offset in bipolar mode.

MONOLITHIC CMOS CONSTRUCTION — The HS 3120 is a one-chip CMOS circuit with a resistor ladder network designed for 0.01% linearity without laser trimming. Small chip size and high manufacturing yields result in greatly reduced cost.

FUNCTIONAL DIAGRAM



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SPECIFICATIONS

MODEL	+10V, unipolar unless otherwise noted). HS 3120-2	HS 3120-0	
	MULTIPLYING, DOUBLE BUFFERED INPUTS	*	
TYPE	MOETH ET MO, DODDE DE		
DIGITAL INPUT	12-Bits	*	
Resolution 2-Quad, Unipolar Coding	Binary ¹ , Comp. Binary ¹	•	
4-Quad, Bipolar Coding	Offset Binary	*	
Logic Compatibility ²	CMOS, TTL	*	
Input Current	±1 μA (max)	*	
Data Set-up Time ³	250nS (min)	i i	
Strobe Width ³	250nS (min)	•	
Data Hold Time ³	OnS (min)		
REFERENCE INPUT			
Voltage Range	±25V (max)	*	
Input Impedance	8kΩ ±50%		
NALOG OUTPUT	105 4 1/4 1500/	*	
Scale Factor	125µA/V _{Ref} ±50% ±0.4%	*	
Scale Factor Accuracy ⁴	±0.4%		
Output Leakage ⁵ @ 25°C	<10nA (max)	*	
@ 125°C	<200nA (max)	*	
Output Capacitance			
COUT 1, all inputs high	80pF	*	
COUT 1, all inputs low	40pF	*	DataS
COLIT 2, all inputs high	40pF	*	Datao
COUT 2, all inputs low	80pF	-	
STATIC PERFORMANCE			
Integral Linearity	±0.015% F.S.R. (max)	±0.05 % F.S.R. (max)	
Differential Linearity	±0.024% F.S.R. (max)	±0.097% F.S.R. (max)	
Monotonicity	Guaranteed to 12 bits	Guaranteed to 10 bits	
Monotonicity Temp. Range	0°C to +70°C	*	
C-Models B-Models	-55°C to +125°C	•	
DYNAMIC PERFORMANCE			
Digital Small Signal Settling	1.0µsec	*	_
Full Scale Transition Settling	1.0µ360		
to 0.01% (strobed)	2.0µsec	•	
Reference Feedthrough Error (VRef = 20Vpp)	DataSheet4U.com	_	
@ 1kHz	<1mV	:	
@ 10kHz	2mV	•	
Delay to output	100-cf	*	
from Bits input	100nS ⁶ 200nS ⁶	*	
from LDAC from CE	120nS ⁶	*	
STABILITY (Over Specified Temp. Range) Scale Factor ⁴	2 ppm F.S.R./°C (max)		
Integral Linearity	0.2 ppm F.S.R./°C (max)	*	
Differential Linearity	0.2 ppm F.S.R./°C (max)	•	
Monotonicity Temp, Range			
C-Option	0°C to +70°C	*	
B-Option	-55°C to +125°C	*	
POWER SUPPLY (VDD)			
Operating Voltage (specifications guaranteed)	+15V ±5%	*	
Maximum Voltage Range	+5V to 16V	*	
Current	2.5mA (max)	*	
Rejection Ratio	0.002%/% (max)	*	
EMPERATURE RANGE			
Operating C-Option	0°C to +70°C	*	
Operating 8-Option	-55°C to +125°C	*	
Storage	-65°C to +150°C	*	
MECHANICAL			
Case Style	28-pin double DIP	*	
C-Option	plastic or ceramic	•	
B-Option	ceramic		

NOTES:

- * Same as HS 3120-2

 1. The input coding is complementary binary if I_{O2} is used.

 2. Digital input voltage must not exceed supply voltage or go below -0.5V.

 "0" < 0.8V, 2.4V < "1" \leq V_{DD}.

 3. All strobes are level triggered. See TIMING DIAGRAM.

 4. Using the internal feedback resistor and an external opamp.

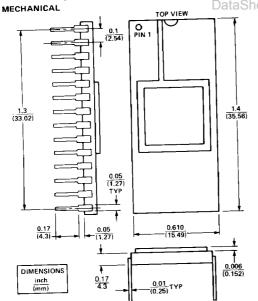
 The output leakage current will create an offset voltage at the external opamps output. It doubles every 10°C temperature increase.
 - 6. Delay times are twice the amount shown at TA = +125°C

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PIN ASSIGNMENTS

PIN ASSIC	INMENTS
PIN	FUNCTION
1	FB ₄ , Feedback Bipolar Operation
2	LDTR, Ladder Termination
3	FB3, Feedback Bipolar Operation
4	VREF, Reference Voltage Input
5	FB ₁ , Feedback, Unipolar/Bipolar
6	IO1, Current out into virtual ground
7	I _{O2} , Current out-complement of I _{O1}
8	V _{SS} , Ground, Analog and DAC Register
9	Bit 1, MSB
10	Bit 2
11	Bit 3
12	Bit 4
13	Bit 5
14	Bit 6
15	Bit 7
16	Bit 8
17	Bit 9
18	Bit 10
19	Bit 11
20	Bit 12
21	LDAC, Transfers data from input to DAC register
22	CE, Chip Enable, active low
23	LBE, Bit 12 to Bit 9 Enable
24	MBE, Bit 8 to Bit 5 Enable
25	HBE, Bit 4 to Bit 1 Enable
26	V _{DD2} , Supply Analog and DAC Register
27	V _{SS1} , Ground input latches
28	V _{DD1} , Supply input latches

NOTE: Pins 8 and 27 and pins 26 and 28 must be connected externally.



CONNECTIONS

Unipolar Operation:

Connect $I_{\mbox{O1}}$ and $\mbox{FB}_{\mbox{1}}$ as shown in diagram. Tie I_{O2} (Pin 7), FB₃ (Pin 3), FB₄, (Pin 1)

all to Ground (Pin 8)

Bipolar Operation:

Connect I O1, I O2, FB1, FB3, FB4 as shown in diagram.

Tie LDTR to I 02

Grounding:

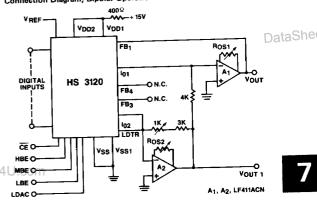
Connect all GRD to system analog ground and tie this to digital ground.

All unused input pins must be grounded. NOTE:

APPLICATIONS INFORMATION

VREF. v_{DD2} FB₁ 101 LDTR DIGITAL HS 3120 FB4 FB3 102 CE O **SS1** HBE O MBE O LBEO

LDAC O Connection Diagram, Bipolar Operation



Connection Diagram, Bipolar Operation (for applications where bipolar offset temperature drift (≈ 10 ppm/°C) is not critical)

NOTE: To maintain specified linearity, external amplifiers must be zeroed. This is best done with VREF set to zero and, Unipolar: load the DAC register with all bits at zero and adjust ROS for VOUT = OV Bipolar; load the DAC register with 10 . . . 0 (MSB =1) and set ROS2 for VOUT 1 = OV. Then set ROS1 for

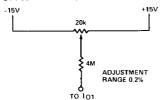
TRANSFER FUNCTION (N=12)

BINARY INPUT	UNIPOLAR OUTPUT	BIPOLAR OUTPUT
111 111	-V _{REF} (1 - 2-N)	-VREF (1 - 2 -(N - 1))
100 001	-V _{REF} (1/2 + 2-N)	-V _{REF} (2 -(N - 1))
100 000	-VREF	0
011111	-V _{REF} (1/2 - 2-N)	V _{REF} (2-(N - 1))
000 000	0	VREF

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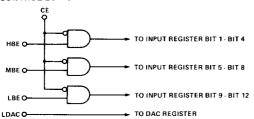
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BIPOLAR OFFSET ADJUST (external)



NOTE: External opamps have to be zeroed before the bipolar offset adjust circuit is connected.

CONTROL LOGIC



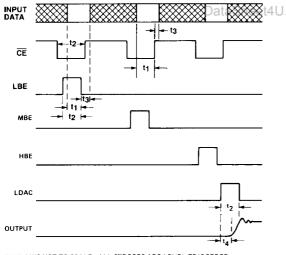
NOTE: The transfer from input register to DAC register can be performed without Enabling Chip.

STROBE LOGIC

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Strobe	Function
0	data latched (held)
1	data changing (transfer)

TIMING DIAGRAM



TIME AXIS NOT TO SCALE, ALL STROBES ARE LEVEL TRIGGERED.

ORDERING INFORMATION

MODEL	DESCRIPTION
HS 3120C-0	Double Buffered 12-Bit MDAC, Commercial
HS 3120C-2	Double Buffered 12-Bit MDAC, Commercial
HS 3120B-0	Double Buffered 12-Bit MDAC, MIL-STD-883C
HS 3120B-2	Double Buffered 12-Bit MDAC, MIL-STD-883C

CAUTION: ESD (Electro-Static Discharge) sensitive device. Permanent damage may occur when unconnected devices are subjected to high energy electrostatic fields. Unused devices must be stored in conductive foam or shunts. Protective foam should be discharged to the destination socket before devices are removed. Devices should be handled at static safe workstations only. Unused digital inputs must be grounded or tied to the logic supply voltage. Unless otherwise noted, the supply voltage at any digital input should never exceed the supply voltage by more than 0.5 volts or go below -0.5 volts. If this condition cannot be maintained, limit input current on digital inputs by using series resistors or contact Hybrid Systems for technical assistance.

Specifications subject to change without notice.

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t₁: Data Setup Time. Time data must be stable before strobe (byte enable/LDAC) goes to "0", t₁ (min) = 250 nsec

 t_2 : Strobe Width, t_2 (min) = 250 nsec, (CE, LBE, MBE, HBE, LDAC).

 t_3 : Hold Time. Time data must be stable after strobe goes to "0", $t_3 = 0$ nsec.

ta: Delay from LDAC to Output, ta = 200 nsec.

NOTE: Minimum common active time for $\overline{\text{CE}}$ and any byte enable is 250 nsec.